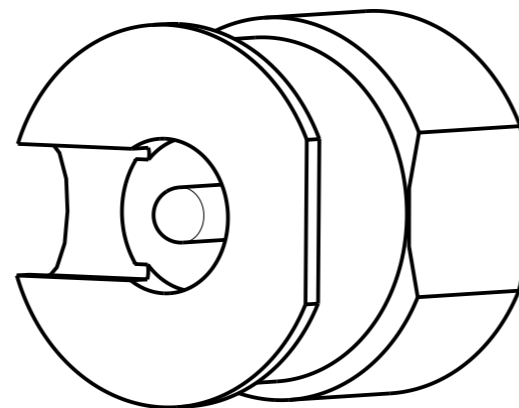
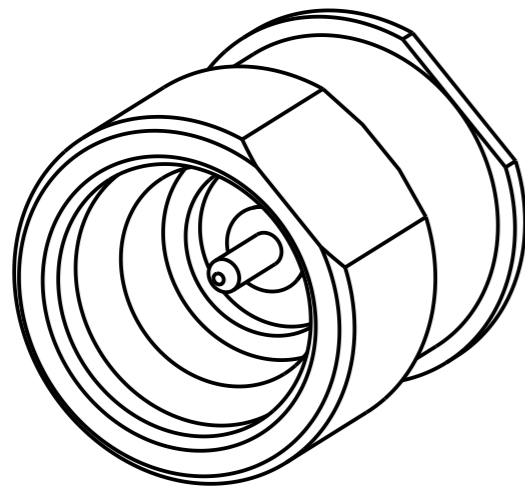
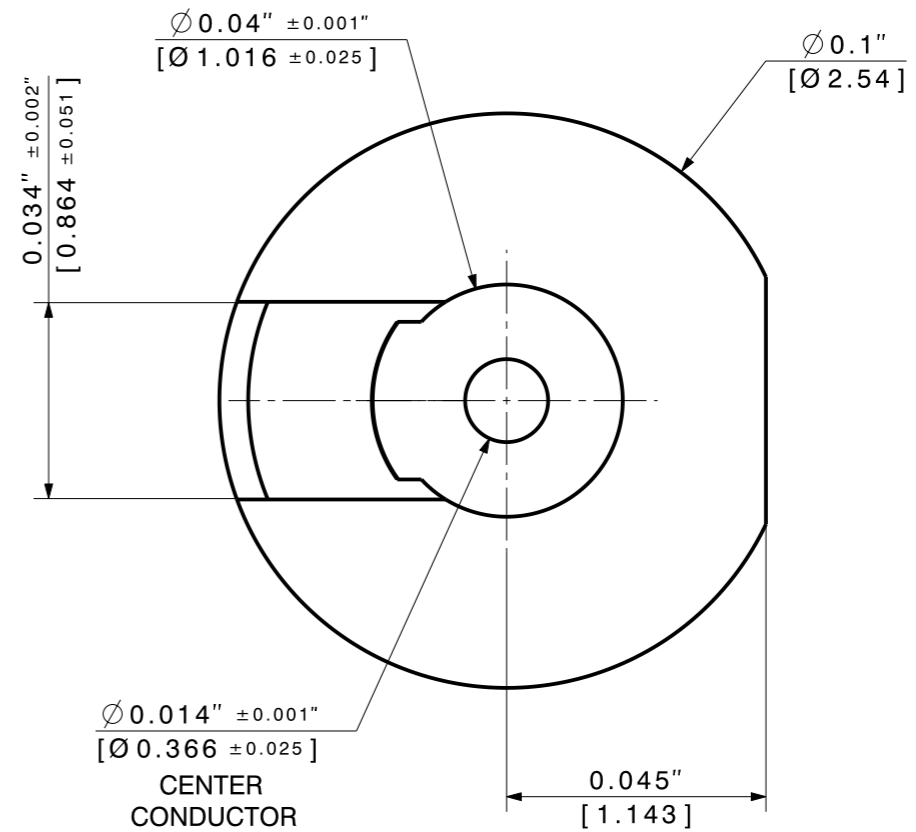
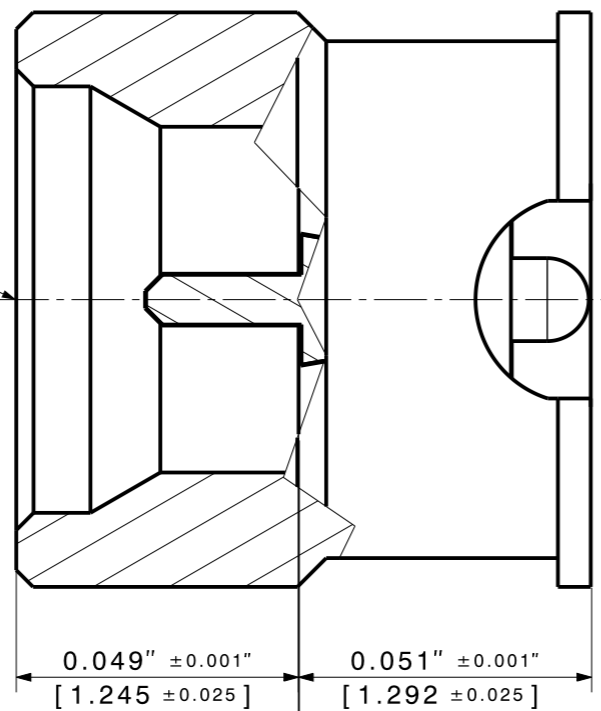


SMP3 Male
Smooth Bore



Component	Material	Material Std compliance	Finish		Finish Std compliance
Body	Beryllium Copper	ASTM B-196 UNS No. C17300 Temper TD04(H)	Gold Plate Nickel underplate	50µIN - 100µIN [1.27µM - 2.54µM]	Gold per ASTM B-488, Code C, Type II, Class 1.27
				50µIN - 100µIN [1.27µM - 2.54µM]	Nickel per SAE-AMS-QQ-N-290, Class I
Insulator	PTFE	ASTM D-1710	---	---	---
Contact	Beryllium Copper	ASTM B-196 UNS No. C17300 Temper TD04(H)	Gold Plate Nickel underplate	50µIN - 100µIN [1.27µM - 2.54µM]	Gold per ASTM B-488, Code C, Type II, Class 1.27
				50µIN - 100µIN [1.27µM - 2.54µM]	Nickel per SAE-AMS-QQ-N-290, Class I

- Interface definition, SMP3 male is designed and manufactured IAW MIL-STD-348 and will mate with SMP3 female connector designed and manufactured IAW MIL-STD-348.
- Mounting Patterns, Customer specific factors including transmission line topology, substrate thickness and material, board-stackup, operating frequency, etc. must be submitted to HUBER+SUHNER Astrolab for analysis prior to release of final performance levels and mounting configuration.

Electrical Specification:
 IMPEDANCE, 50.0 Ohms NOMINAL.
 FREQUENCY, 65.0 GHz.

Mechanical:
 Operating temperature range: -55° C to +165° C.

Type: 81 SMP3-S50-0-SB1		All dimensions after treatment in millimeter (mm)	
Assembly drawing	Released date: 01.11.2022	alternative ID 29174SM-4-001 3D-ID PRO-01167180 A	Sheet: 1 / 1
HUBER+SUHNER		description SMP3 Smooth Bore Surface Mount	ID DOU-01171676 A